



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DZ2W27000L

Silicon epitaxial planar type

For constant voltage / For surge absorption circuit
 DZ24270 in Mini2 type package

■ Features

- Excellent rising characteristics of zener current I_Z
- Low zener operating resistance R_Z
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: FG

■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	500	mA
Forward current	IF	200	mA
Total power dissipation *1	PT	1	W
Non-repetitive reverse power surge *2	PZSM	100	W
Electrostatic discharge *3	ESD	±30	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note: *1 Mounted on ceramics print circuit board.

Board size: 50 mm × 50 mm

Board thickness: 0.8 mm

Soldering size: 2 mm × 2 mm

*2 t = 0.1ms

*3 Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)

■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 200 mA			1.2	V
Zener voltage *1, *2	VZ	IZ = 10 mA	25.65	27.00	28.35	V
Zener operating resistance	RZ	IZ = 10 mA			30	Ω
Reverse current	IR	VR = 19.0 V			10	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 10 mA		27.0		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

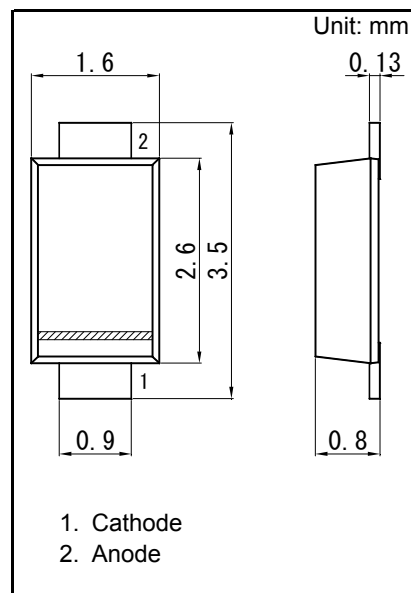
2. Absolute frequency of input and output is 5 MHz.

3. *1 The temperature must be controlled 25°C for VZ measurement.

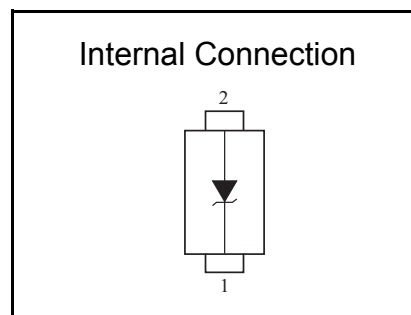
VZ value measured at other temperature must be adjusted to VZ (25°C)

*2 VZ guaranteed 20 ms after current flow.

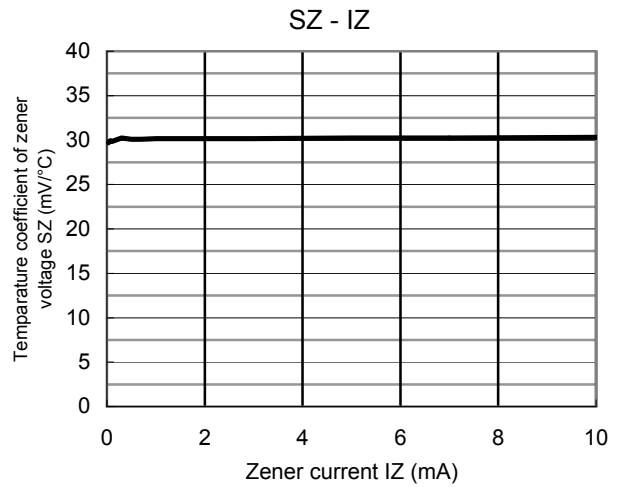
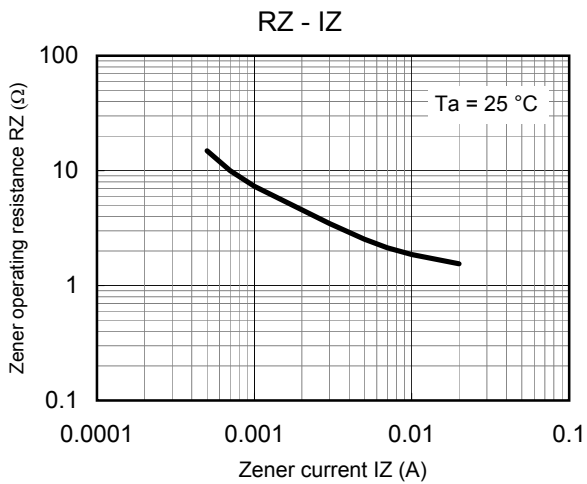
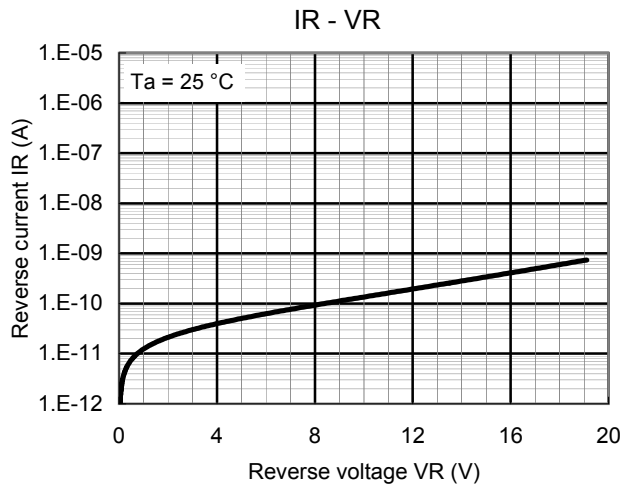
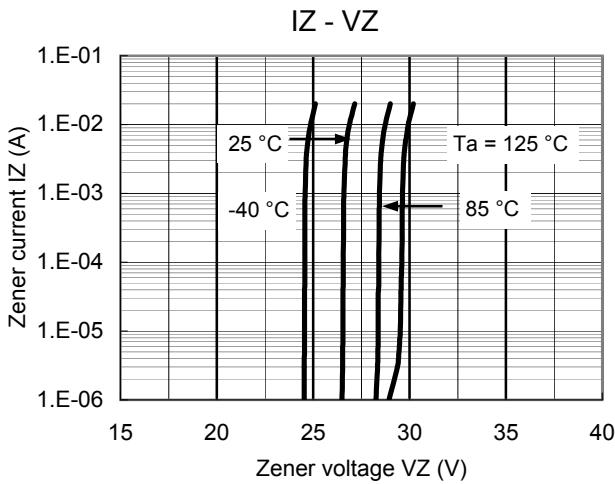
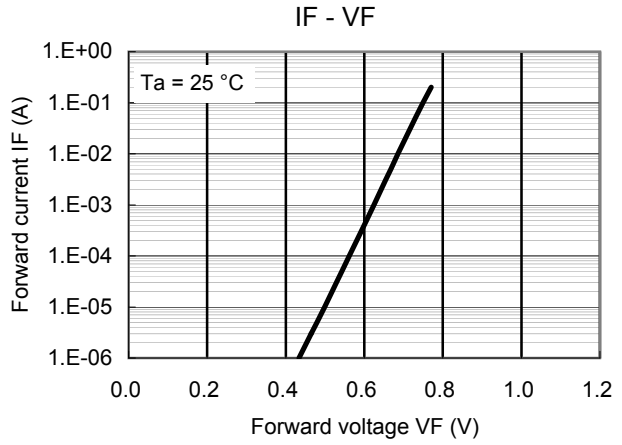
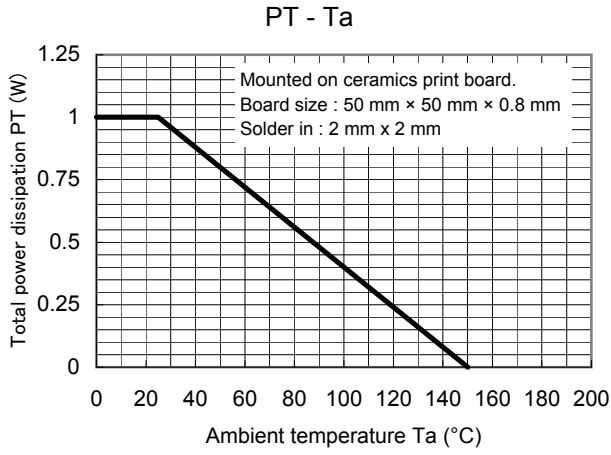
*3 Tj = 25°C to 150°C



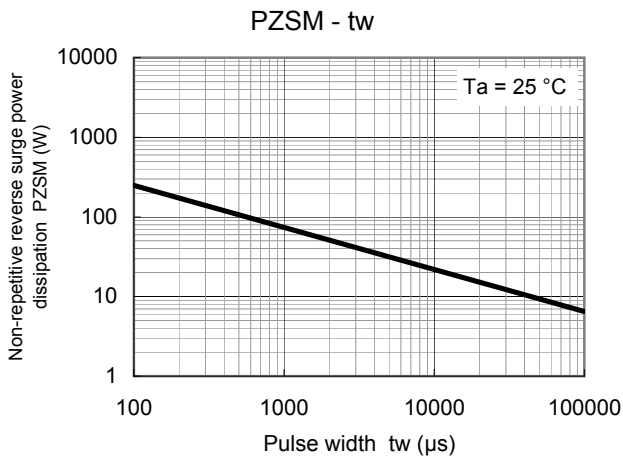
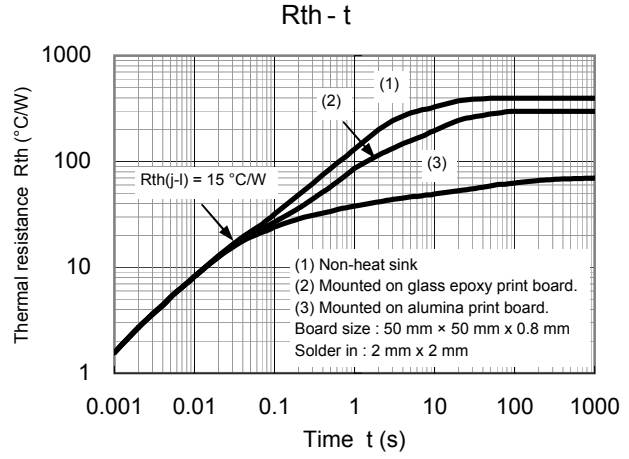
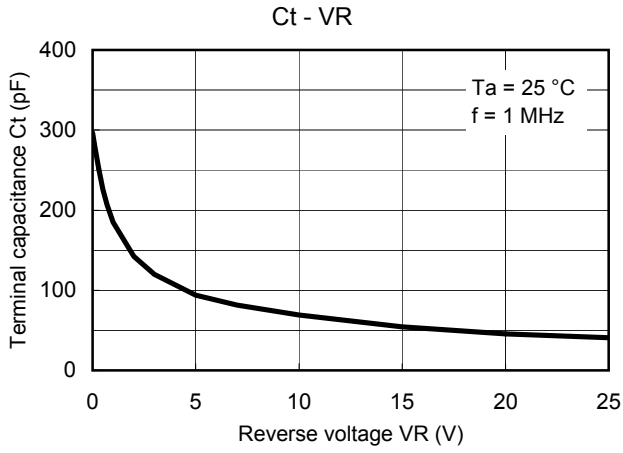
Panasonic	Mini2-F3-B
JEITA	SC-109B
Code	—



Technical Data (reference)



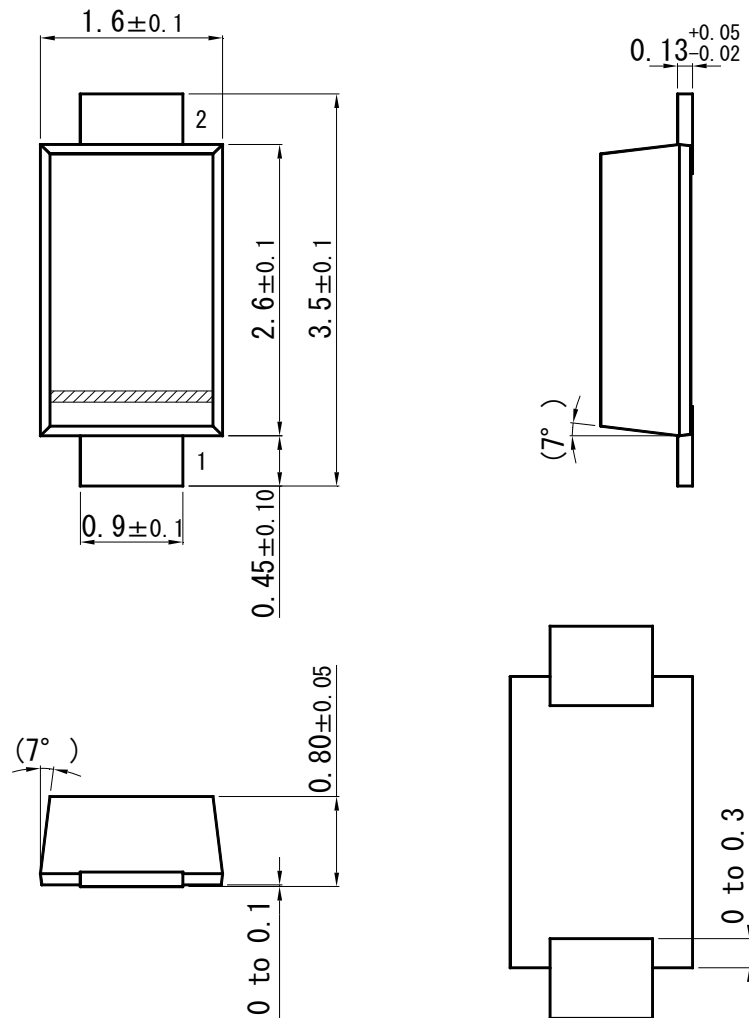
Technical Data (reference)



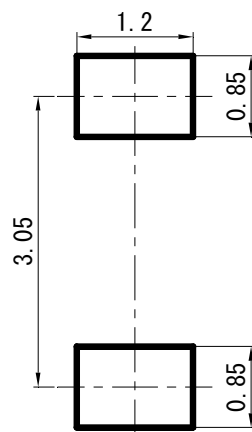


Mini2-F3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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